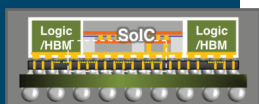
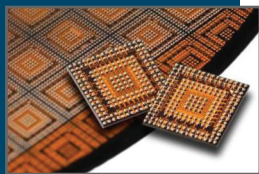


Advanced Packaging Update: Market and Technology Trends

Vol. 4-0120



This issue of the Advanced Packaging Update features special coverage of large area panel fan-out wafer level packaging (FO-WLP) developments. The panel market is divided into high-density RDL ($\leq 2\mu\text{m}$ L/S with multiple RDLs) versus low-density ($> 5\mu\text{m}$ L/S with ≤ 3 RDLs). Panel activities at major organizations are discussed and a market forecast for low-density panels is included. High-performance packaging options including silicon interposers and alternatives such as fan-out on substrate are presented. A special section examines developments in electro-magnetic interference (EMI) shielding. Huawei's new 5G smartphone is examined. Outsourced semiconductor assembly and test (OSAT) financials are analyzed.

Table of Contents

1 Industry and Economic Trends

- 1.1 Macroeconomic Trends
- 1.2 Trade Tensions Continue
 - 1.2.1 U.S. and China Conflict
 - 1.2.2 Huawei's Smartphones
 - 1.2.2.1 Packages in Mate 30 5G
 - 1.2.2.2 Comparison with Mate 20X 5G
 - 1.2.3 Japan and South Korea Conflict
- 1.3 Semiconductor Sector

2 OSAT Financial Analysis

- 2.1 Definitions
- 2.2 OSAT Market Performance
- 2.3 Outlook

3 Fan-Out Panel Developments

- 3.1 Panel Drivers
- 3.2 Panel Applications
 - 3.2.1 Application Processor and PMIC
 - 3.2.2 Image Sensor
 - 3.2.3 Memory
 - 3.2.4 Antenna-in-Package for 5G
- 3.3 Challenges for Panel Production
- 3.4 Company Activities
 - Amkor, ASE, China Wafer Level CSP, Nepes, PTI, Samsung, Unimicron
- 3.5 Research Consortia
 - ASM Pacific's FOP-WLP Consortium, Fraunhofer IZM, IME A*STAR, iNEMI, JOINT Consortium, NCAP
- 3.6 FO Panel Capacity and Market Forecast

4 High-Performance Package Trends

- 4.1 Package Trade-offs
 - 4.1.1 Amkor Technology
 - 4.1.2 ASE
 - 4.1.3 TSMC's High-Density Options
 - 4.1.4 TSMC's Organic RDL Interposer
 - 4.1.5 High-Density FO and Si Interposer Forecast

5 EMI Shielding

- 5.1 EMI Shielding in Smartphones

2019 BGA and CSP Bibliography

References

List of Figures

- 1.1. Monthly U.S. housing starts.
- 2.1. Quarterly revenue for top 20 OSATs.
- 3.1. Mold-first FOPLP process flows.
- 3.2. Samsung's smartwatch module.
- 3.3. FO-WLP for image sensor.
- 4.1. Polyimide stress contours of the RDL.
- 4.2. Normalized polyimide stress on RDLs.

List of Tables

- 1.1. Mate 30 5G Package Types
- 1.2. Mate 30 5G Package Examples
- 1.3. Mate 20X 5G and Mate 30 5G Comparison
- 3.1. Panel Economics Depends on Package Size
- 3.2. Samsung Galaxy Watch Module Measurements
- 3.3. FO-WLP Panel Activities
- 3.4. RDL Interposer Panel Activities
- 3.5. PTI's Panel Fan-Out WLP Options
- 3.6. FO-WLP Panel Consortia
- 3.7. Forecast for Low-Density Panel Demand
- 3.8. Estimated Annual Low-Density Panel Capacity
- 4.1. High-Density Package Performance Metrics
- 4.2. 3D SoIC for Logic + Memory Integration
- 4.3. Markets for Si Interposer and HPC HD FO
- 5.1. iPhone 11 Pro Max and Conformal Shielding

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